



# Asetek Announces Names of Undisclosed OEM Partner and HPC Customer

**November 15, 2016** – With reference to stock exchange notice June 22, 2016 announcing that Asetek had received an order from one of its existing OEM partners for RackCDU D2C™ (Direct-to-Chip) to satisfy an undisclosed HPC customer installation in Europe, resulting in revenue to Asetek in the range of \$100,000 with installation expected to occur in Q3 2016:

Asetek® today announces that its existing OEM partner Fujitsu® that has been selected by the University of Regensburg to install Asetek InRackCDU™ technology to liquid cool one of the first Intel® Xeon Phi™ based HPC clusters in Europe. The Fujitsu® installation is a joint research project (SFB/TRR-55) with The University of Wuppertal and Jülich Supercomputing Center.

"We appreciate that our OEM customer Fujitsu continue to deploy Asetek's liquid cooling solution and increase end user adoption" said André Sloth Eriksen, Founder and CEO of Asetek.

For the full press release go to [www.asetek.com](http://www.asetek.com).

## About Asetek

Asetek® (ASETEK.OL) is the global leader in liquid cooling solutions for data centers, servers and PCs. Asetek's server products enable OEMs to offer cost effective, high performance liquid cooling data center solutions. Its PC products are targeted at the gaming and high performance desktop PC segments. With over 3.5 million liquid cooling units deployed, Asetek's patented technology is being adopted by a growing portfolio of OEMs and channel partners. Founded in 2000, Asetek is headquartered in Denmark and has operations in California, Texas, China and Taiwan. For more information visit <http://www.asetek.com>.

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